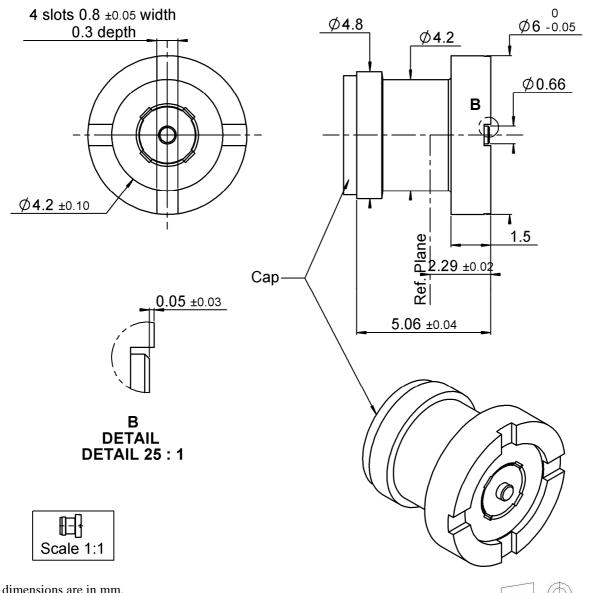
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Series : **SMP LOCK**



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRASS BERYLLIUM COPPER - PTFE - PTFE	N2PGR N2PGR -	
-	-	-	

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In the effort to improve our products, we reserve the right to make changes judged to be



MALE STRAIGHT RECEPTACLE FOR PCB

LIMITED DETENT REEL 100

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Series: SMP LOCK

PACKAGING

Standard	Unit	Other	
100	W	Contact us	

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-18} \;\; \text{GHz} \end{array}$

VSWR 1.05* + 0,0170 x F(GHz) Maxi

Insertion loss RF leakage 0.12 $\sqrt{F(GHz)}$ dB Maxi - (90* - F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 500 M Ω mini

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

*Coaxial Transmission Line Only

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.7 N mini
6.7 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0,5700** g

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ecessary.

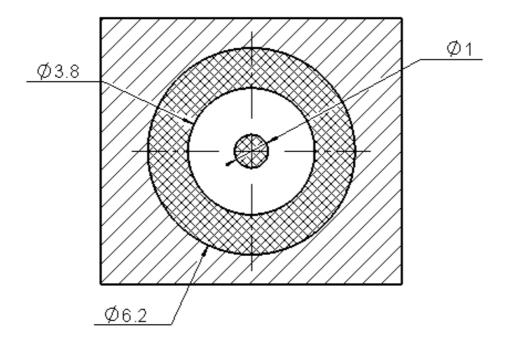
Issue: 1312

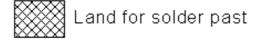


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Series : **SMP LOCK**

STANDARD PAD (RADIALL RECOMMANDATION)







- -The landing pad for center contact should be linked to the stripline using a filled via.
- -Upper and lower ground planes should be linked using vias.

Issue: 1312 A

In the effort to improve our products, we reserve the right to make changes judged to be

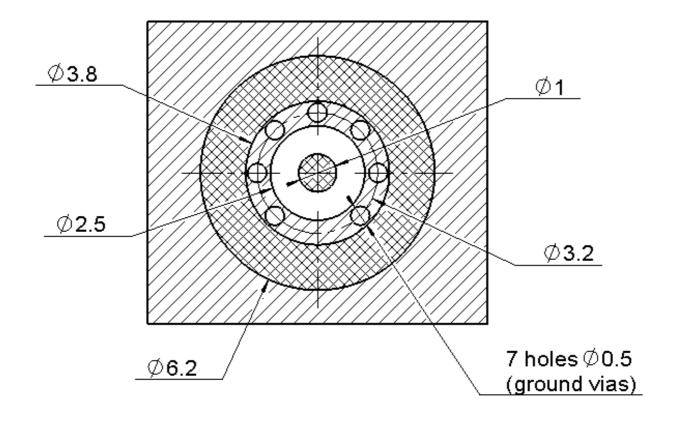
ecessary.

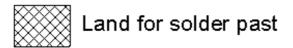


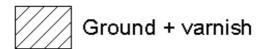
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Series: SMP LOCK

RT DUROID 6002 (30 mils) PAD (RADIALL RECOMMANDATION)







- -The landing pad for center contact should be linked to the stripline using a filled via.
- -Upper and lower ground planes should be linked using vias.

Issue: 1312

In the effort to improve our products, we reserve the right to make changes judged to be



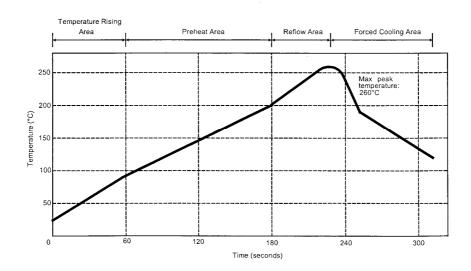
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Series: SMP LOCK

SOLDER PROCEDURE

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 μm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .

Verification of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

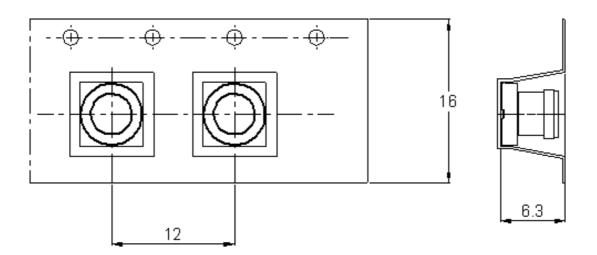
Issue: 1312 A

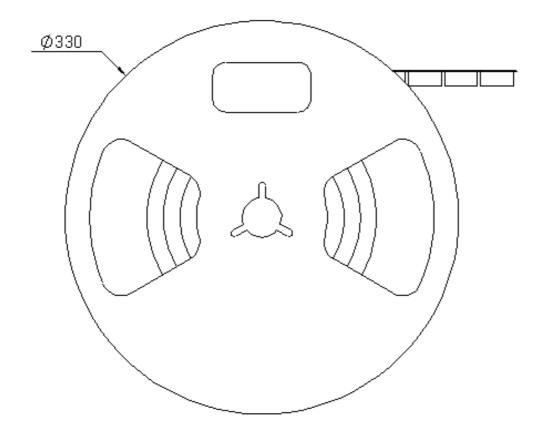
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